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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10082010	FILING DATE 02/22/2002	CLASS 438	SUBCLASS 79	GAU 2813	EXAMINER <i>W...</i>
**APPLICANTS: Singh Rajiv; Lee Seung-Mahn;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 5853-224	
TITLE : Slurry and method for chemical mechanical polishing of metal structures including refractory metal based barrier layers					
U.S.DEP'T. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)					

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NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED		
Assistant Examiner				
		DRAWING		
		Sheets Drwg.	Figa.Drwg.	Print Fig.
Primary Examiner				
PREPARED FOR ISSUE		Application Examiner		
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